

ABSTRACT OF THE DISCLOSURE

To provide an exposure apparatus with which a wafer surface to be exposed can be aligned with a best imaging plane with respect to a reduced focal
5 depth and a high resolution can be attained. The exposure apparatus for exposing a pattern formed on a reticle to an object to be exposed includes: a detecting unit for measuring a position of the object to be exposed at a plurality of first measurement
10 positions that meet a predetermined relative positional relationship in an exposure region of the object to be exposed to which the pattern is exposed and for measuring a position of the object to be exposed at a plurality of second measurement
15 positions that meet the predetermined relative positional relationship in regions outside the exposure region; and a control unit for controlling at least one of a position, a height, and a tilt of the object to be exposed based on information on the
20 position of the object to be exposed which is measured by the detecting unit.